

PATENT ASSIGNMENT

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SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Manoj Vellaikal	01/30/2006
Hemant P. Mungekar	01/30/2006
Young S. Lee	01/30/2006
Yasutoshi Okuno	02/20/2006
Hiroshi Yuasa	02/20/2006

RECEIVING PARTY DATA

Name:	Applied Materials, Inc.
Street Address:	P. O. Box 450A
City:	Santa Clara
State/Country:	CALIFORNIA
Postal Code:	95052

Name:	Matsushita Electric Industrial Co., Ltd.
Street Address:	1006 Oaza Kadoma, Kadoma-shi
City:	Osaka
State/Country:	JAPAN
Postal Code:	571-8501

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11166357

CORRESPONDENCE DATA

Fax Number: (408)986-3090

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Email: barbara_holt@amat.com

Correspondent Name: Applied Materials

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PATENT
REEL: 017260 FRAME: 0104

Address Line 4: Santa Clara, CALIFORNIA 95052

ATTORNEY DOCKET NUMBER:

10189/DSM/HDP/CVD

NAME OF SUBMITTER:

Barbara Holt

Total Attachments: 4

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ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Manoj Vellaikal of 3707 Poinciana Drive, #68, Santa Clara, CA 95051; Hemant P. Mungekar of 515 Boynton Ave., Apt 29, San Jose, CA 95117; and Young S. Lee of 1526 Vista Club Circle #209, Santa Clara, CA 95054, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: GAPFILL USING DEPOSITION-ETCH SEQUENCE

Date(s) of execution of Declaration:

Filing Date: June 24, 2005

Application No.: 11/166,357; and

WHEREAS, APPLIED MATERIALS, INC., a corporation of the state of Delaware, located at Legal Affairs Department, 3050 Bowers Avenue, M/S 2061, Santa Clara, CA 95054, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

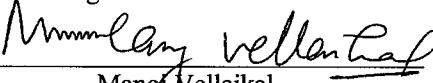
Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Said Assignors acknowledge that Yasutoshi Okuno and Hiroshi Yuasa are assigning all of their respective rights, title and interest in said application to Matsushita Electric Industrial Co., Ltd., a Japanese corporation having a place of business at 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, JAPAN.

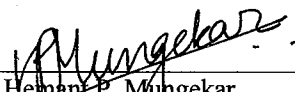
Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

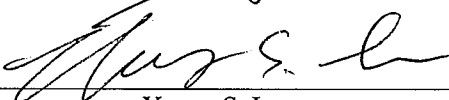
Dated: 1-30-2006


Manoj Vellaikal

Dated: 1-30-2006


Hemant P. Mungekar

Dated: 1/30/2006


Young S. Lee

60679461 v1

ASSIGNMENT OF PATENT APPLICATION

JOINT

WHEREAS, Yasutoshi Okuno of 8-16-4 Hikari-dai, Seika-cho, Soraku-gun, Kyoto, 619-0237 Japan; and Hiroshi Yuasa of 3-16-13 Seika-dai, Seika-cho, Soraku-gun, Kyoto, 619-0238 Japan, hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: GAPFILL USING DEPOSITION-ETCH SEQUENCE

Date(s) of execution of Declaration:

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Application No.: 11/166,357; and

WHEREAS, Matsushita Electric Industrial Co., Ltd. of 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501, JAPAN, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same;

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

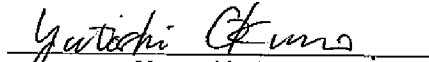
Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

Said Assignors acknowledge that Manoj Vellaikal, Hemant P. Mungekar and Young S. Lee are assigning all of their respective rights, title and interest in said application to Applied Materials, Inc., a corporation of the state of Delaware, having a place of business at 3050 Bowers Avenue, Legal Affairs Department, M/S 2061, Santa Clara, CA 94054.

Assignors hereby authorize and request Townsend and Townsend and Crew LLP, Two Embarcadero Center, Eighth Floor, San Francisco, CA 94111-3834, to insert herein above the application number and filing date of said application when known.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated: February 20, 2006


Yasutoshi Okuno

Assignment

Attorney Docket No.: A10189/T62700

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Dated: Feb. 20, 2006

Hiroshi Yuasa
Hiroshi Yuasa

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RECORDED: 03/06/2006

PATENT
REEL: 017260 FRAME: 0109